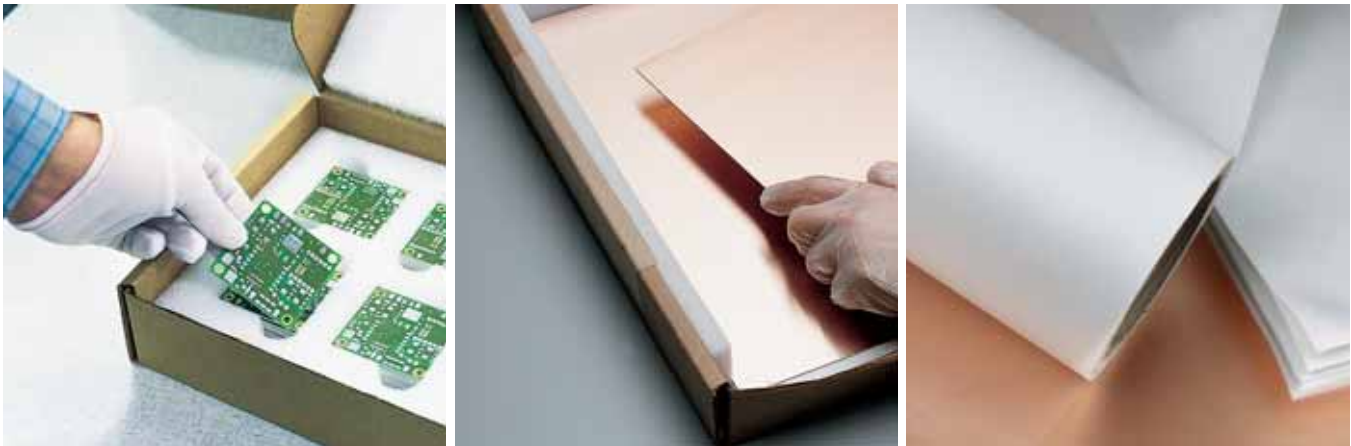


# Thermal Clad Configurations



## Custom Circuit

Bergquist Thermal Clad substrates are custom configured to your design parameters at our Prescott, Wisconsin facility. Our field application support personnel in conjunction with our mechanical and process engineers are available to assist you in taking your design from paper to finished product. Engineering is available for the following construction parameters and options.

- Artwork layout recommendations
- Base metal requirements and mechanical configuration
- Dielectric thickness
- Copper weights (18-350 $\mu$ m / .5-10 oz)
- Solder mask layouts
- All common circuit finishes
- Tooling/singulation options

## Panel Form

Additional base metal sizes and thickness options are available

### Dimensions:

- 18" x 24" (457mm x 610mm)
- 18" x 25" (457mm x 635mm)
- 20" x 24" (508mm x 610mm)
- Foil Thickness: 18-350 $\mu$ m (.5-10 oz)

### Base Plate Metals:

- Aluminum 6061-T6, 5052-H34, standards from 0.020" to 0.190" (0.5mm to 4.83mm)
- Copper 110 Full-Hard, standard from 0.020" to 0.125" (0.5mm to 3.2mm)

## Sheet And Roll Format

CML (Circuit Material Laminate) is a ceramic filled polymer that forms a strong, thermally conductive bond to metal heat spreaders and is an excellent alternative to pre-preg.

- 24" (610mm) Roll Standard (custom sizes are available)
- Maximum roll length of 2000' (610m)
- Sheets 18"x 24" (457mm x 610mm) and 20" x 24" (508mm x 610mm)

## U.L. Certifications Directory

For information regarding the U.L. recognition status of Bergquist Thermal Clad materials and "Prescott Operations" circuit fabrication, the U.L. website provides the latest information.

Using the address: <http://www.ul.com> select; Online Certifications Directory. Enter one of the following file numbers: U.L. File Number, to the applicable Bergquist file.

- In each group there is guide information which will give a further description of the categories listed.
- In each group the recognized materials or fabricated circuit board types will be listed.

### QMTS2.E121882

*Polymeric Materials - Filament-wound tubing, Industrial Laminates, Vulcanized Fiber, and Materials for Use in Fabricating Recognized Printed Wiring Boards - Components.*

### ZPMV2.E122713

*Wiring, Printed - Component*